

MODULATED FLIP CHIP SUBSTRATE DESIGN

Abstract of the Disclosure

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Methods and apparatus are provided for designing the electrical interconnects of a substrate. Modules are used to design sections of the electrical interconnects. Multiple modules may be interconnected to generate the electrical interconnects. The placement of modules and/or the interconnection of the modules may depend on a netlist and/or a separate report. Modules may even be defined by various constraints. Accordingly, a module based design may be implemented for efficiently and effectively producing a standardized electrical interconnect design.

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